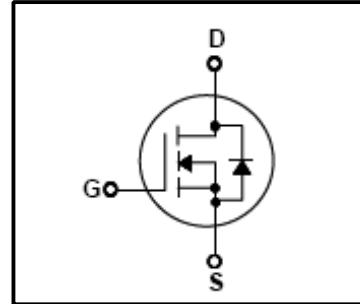


**Silicon N-Channel MOSFET**

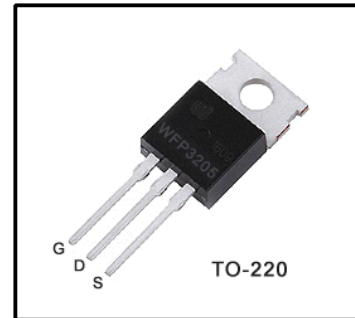
**Features**

- 110A,50V,  $R_{DS(on)}$ (Max 8m $\Omega$ )@ $V_{GS}=10V$
- Ultra-low Gate charge(Typical133nC)
- Fast Switching Capability
- 100%Avalanche Tested
- Maximum Junction Temperature Range(150 $^{\circ}C$ )



**General Description**

This Power MOSFET is produced using Winsemi's advanced planar stripe,DMOS technology. This latest technology has been especially designed to minimize on-state resistance ,have a lowgate charge with superior switching performance ,and ruggedavalanche characteristics.This Power MOSFET is well suited for synchronous DC-DC Converters and power Management inportable and battery operated products.



**Absolute Maximum Ratings**

Symbol	Parameter	Value	Units
$V_{DSS}$	Drain Source Voltage	50	V
$I_D$	Continuous Drain Current(@ $T_c=25^{\circ}C$ )	110	A
	Continuous Drain Current(@ $T_c=100^{\circ}C$ )	80	A
$I_{DM}$	Drain Current Pulsed (Note1)	390	A
$V_{GS}$	Gate to Source Voltage	$\pm 20$	V
$E_{AR}$	Repetitive Avalanche Energy (Note1)	20	mJ
$dv/dt$	Peak Diode Recovery $dv /dt$ (Note3)	5.0	V/ ns
$P_D$	Total Power Dissipation(@ $T_c=25^{\circ}C$ )	200	W
	Derating Factor above 25 $^{\circ}C$	1.3	W/ $^{\circ}C$
$T_J, T_{stg}$	Junction and Storage Temperature	-55~150	$^{\circ}C$
$T_L$	Channel Temperature	300	$^{\circ}C$

**Thermal Characteristics**

Symbol	Parameter	Value			Units
		Min	Typ	Max	
$R_{QJC}$	Thermal Resistance , Junction -to -Case	-	-	0.75	$^{\circ}C/W$
$R_{QCS}$	Thermal Resistance , Case-to-Sink	-	0.5	-	$^{\circ}C/W$
$R_{QJA}$	Thermal Resistance , Junction-to -Ambient	-	-	62	$^{\circ}C/W$

**Electrical Characteristics(Tc=25°C)**

Characteristics		Symbol	Test Condition	Min	Type	Max	Unit
Gate leakage current		I <sub>GSS</sub>	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V	-	-	±100	nA
Gate-source breakdown voltage		V <sub>(BR)GSS</sub>	I <sub>G</sub> =±10 μA, V <sub>DS</sub> =0V	±30	-	-	V
Drain cut -off current		I <sub>DSS</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V	-	-	10	μA
Drain -source breakdown voltage		V <sub>(BR)DSS</sub>	I <sub>D</sub> =250 μA, V <sub>GS</sub> =0V	50	-	-	V
Breakdown voltage Temperature Coefficient		ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	I <sub>D</sub> =1mA, Referenced to 25 °C	-	0.057	-	V/°C
Gate threshold voltage		V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	2	-	4	V
Drain -source ON resistance		R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =60A	-	-	8.0	mΩ
Forward Transconductance		g <sub>fs</sub>	V <sub>DS</sub> =25V, I <sub>D</sub> =60A	44	-	-	S
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> =25V,	-	3247	-	pF
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>GS</sub> =0V,	-	211	-	
Output capacitance		C <sub>oss</sub>	f=1MHz	-	781	-	
Switching time	Rise time	t <sub>r</sub>	V <sub>DD</sub> =28V,	-	101	-	ns
	Turn-on time	t <sub>on</sub>	I <sub>D</sub> =60A	-	14	-	
	Fall time	t <sub>f</sub>	R <sub>G</sub> =4.5Ω	-	65	-	
	Turn-off time	t <sub>off</sub>	V <sub>GS</sub> =10V (Note4,5)	-	50	-	
Total gate charge(gate-source plus gate-drain)		Q <sub>g</sub>	V <sub>DS</sub> =44V, V <sub>GS</sub> =10V,	-	133	146	nC
Gate-source charge		Q <sub>gs</sub>	I <sub>D</sub> =60A	-	-	35	
Gate-drain("miller") Charge		Q <sub>gd</sub>	(Note4,5)	-	-	54	

**Source-Drain Ratings and Characteristics(Ta=25°C)**

Characteristics	Symbol	Test Condition	Min	Type	Max	Unit
Continuous drain reverse current	I <sub>DR</sub>	-	-	-	110	A
Pulse drain reverse current	I <sub>DRP</sub>	-	-	-	390	A
Forward voltage(diode)	V <sub>DSF</sub>	I <sub>DR</sub> =60A, V <sub>GS</sub> =0V	-	-	1.4	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> =60A, V <sub>GS</sub> =0V,	-	69	104	ns
Reverse recovery charge	Q <sub>rr</sub>	di <sub>DR</sub> / dt =100 A / μs	-	143	215	μC

Note 1.Repeativity rating :pulse width limited by junction temperature

2.L=138uH I<sub>AS</sub>=60A,,R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25 °C

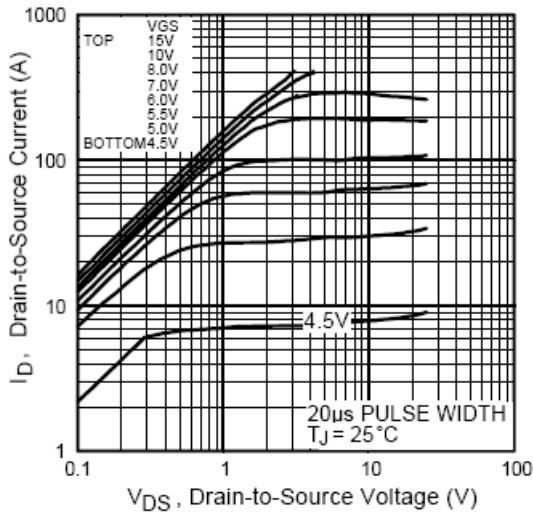
3.I<sub>SD</sub>≤60A, di/dt≤207A/us, V<sub>DD</sub><BV<sub>DSS</sub>, T<sub>J</sub>≤150 °C

4.Pulse Test:Pulse Width≤400us,Duty Cycle≤2%

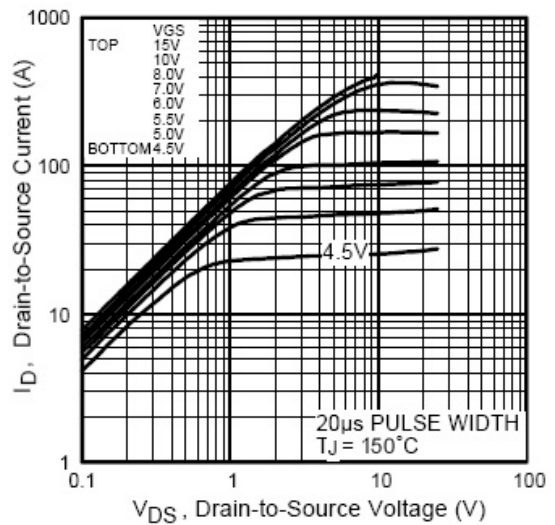
5. Essentially independent of operating temperature.

This transistor is an electrostatic sensitive device

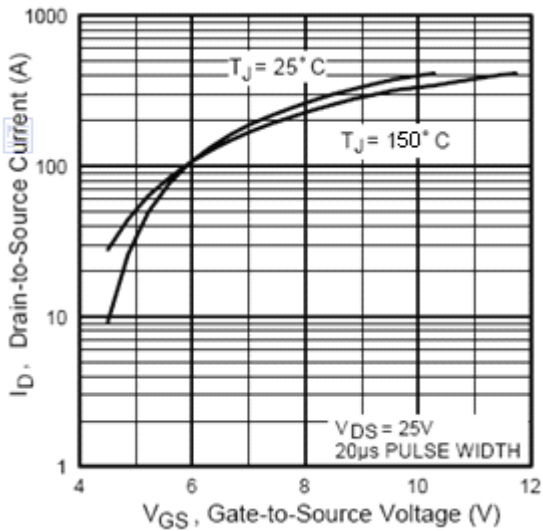
Please handle with caution



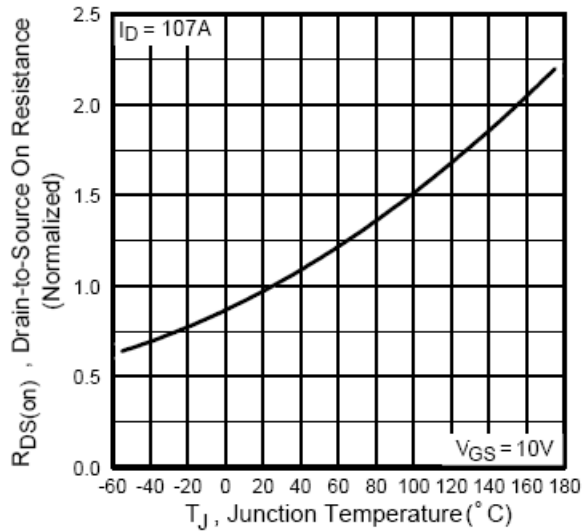
**Fig.1 On State Characteristics**



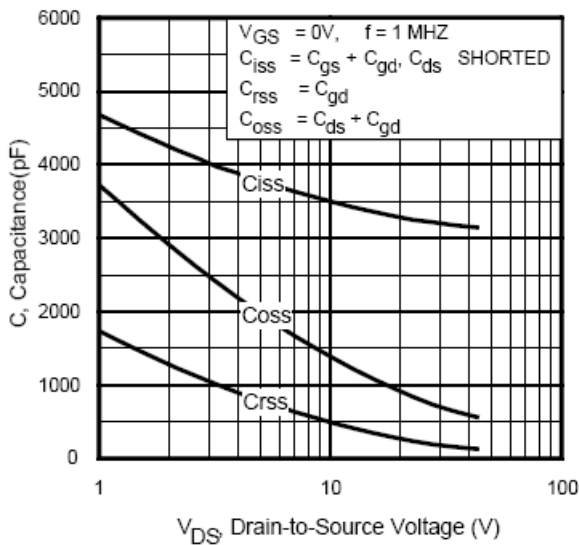
**Fig.2 On State Characteristics**



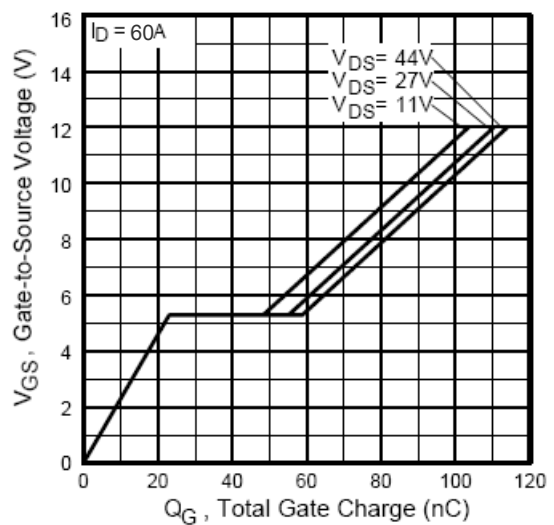
**Fig.3 Transfer Characteristics**



**Fig.5 On-Resistance Variation vs Junction temperature**

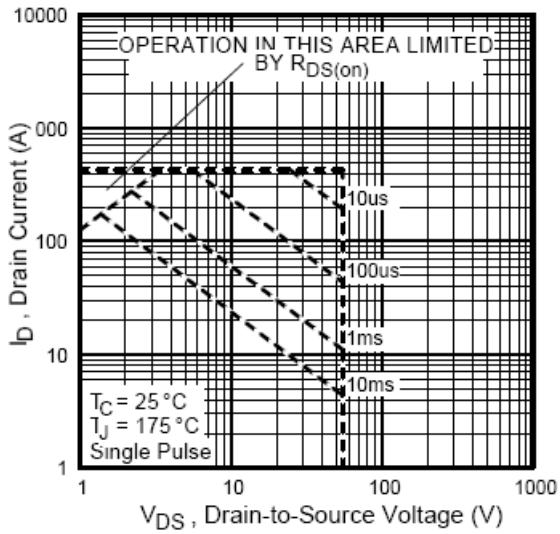


**Fig.5 Capacitance Variation vs Drain Voltage**

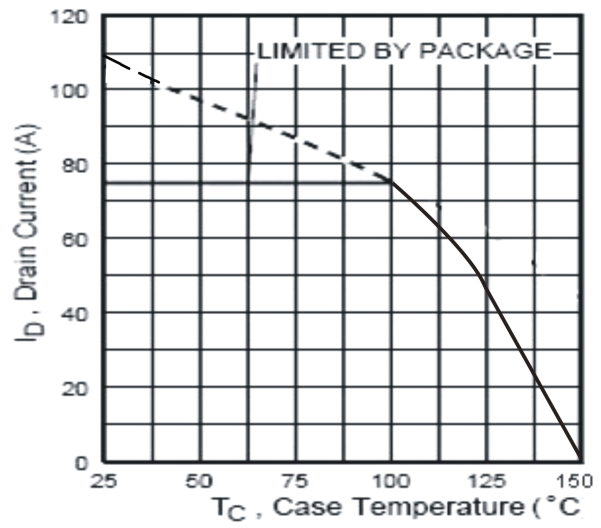


**Fig.6 Gate Charge Characteristics**

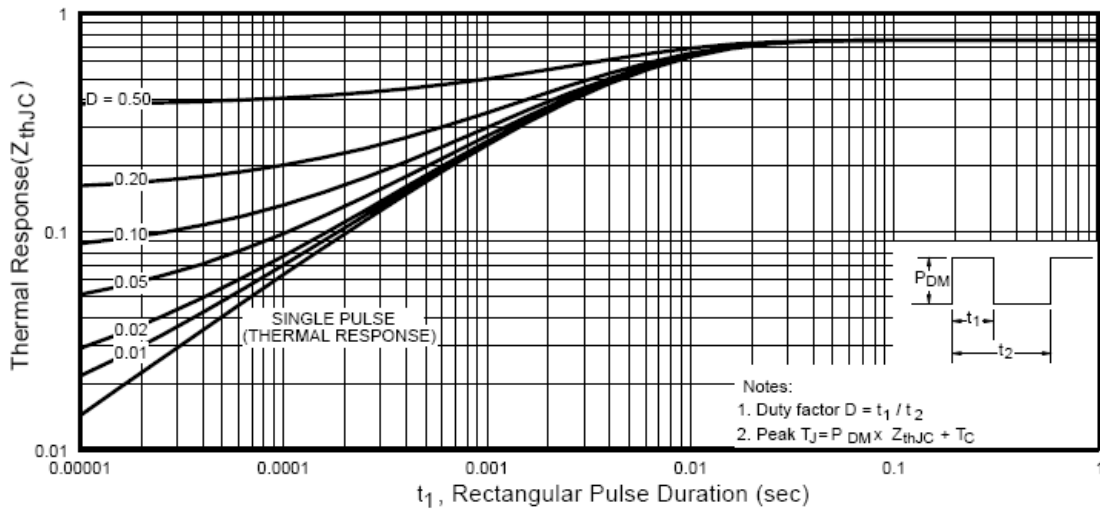




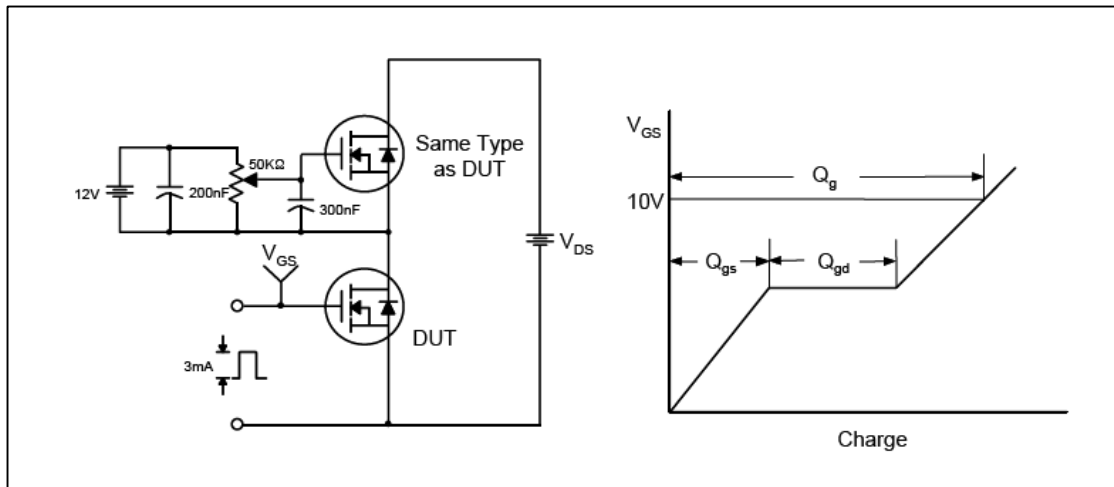
**Fig.7 Maximum Safe Operation Area**



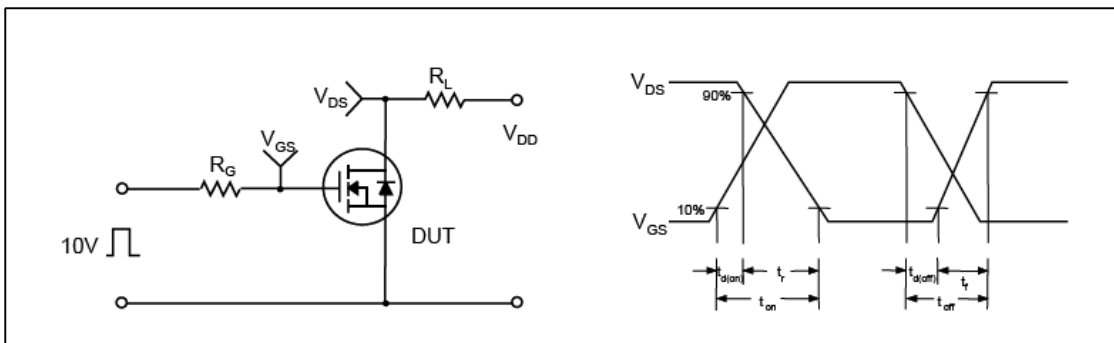
**Fig.8 Maximum Drain Current vs Case temperature**



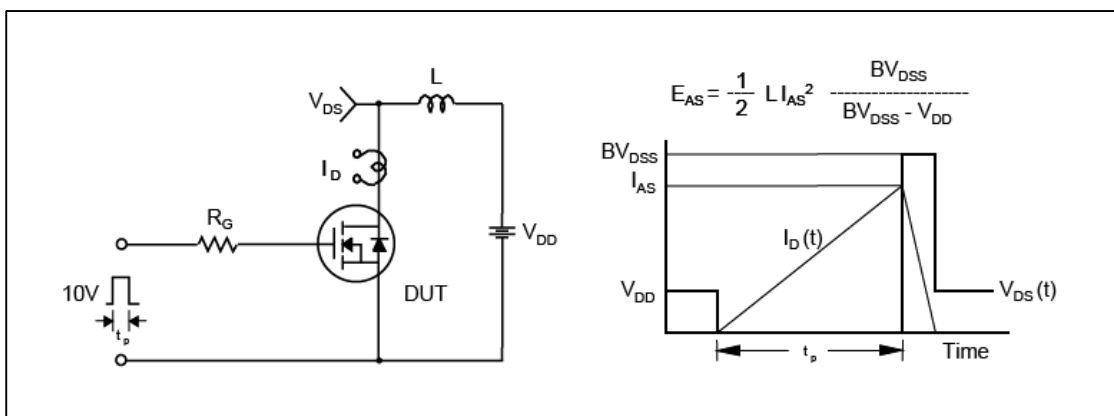
**Fig.9 Transient thermal Response Curve**



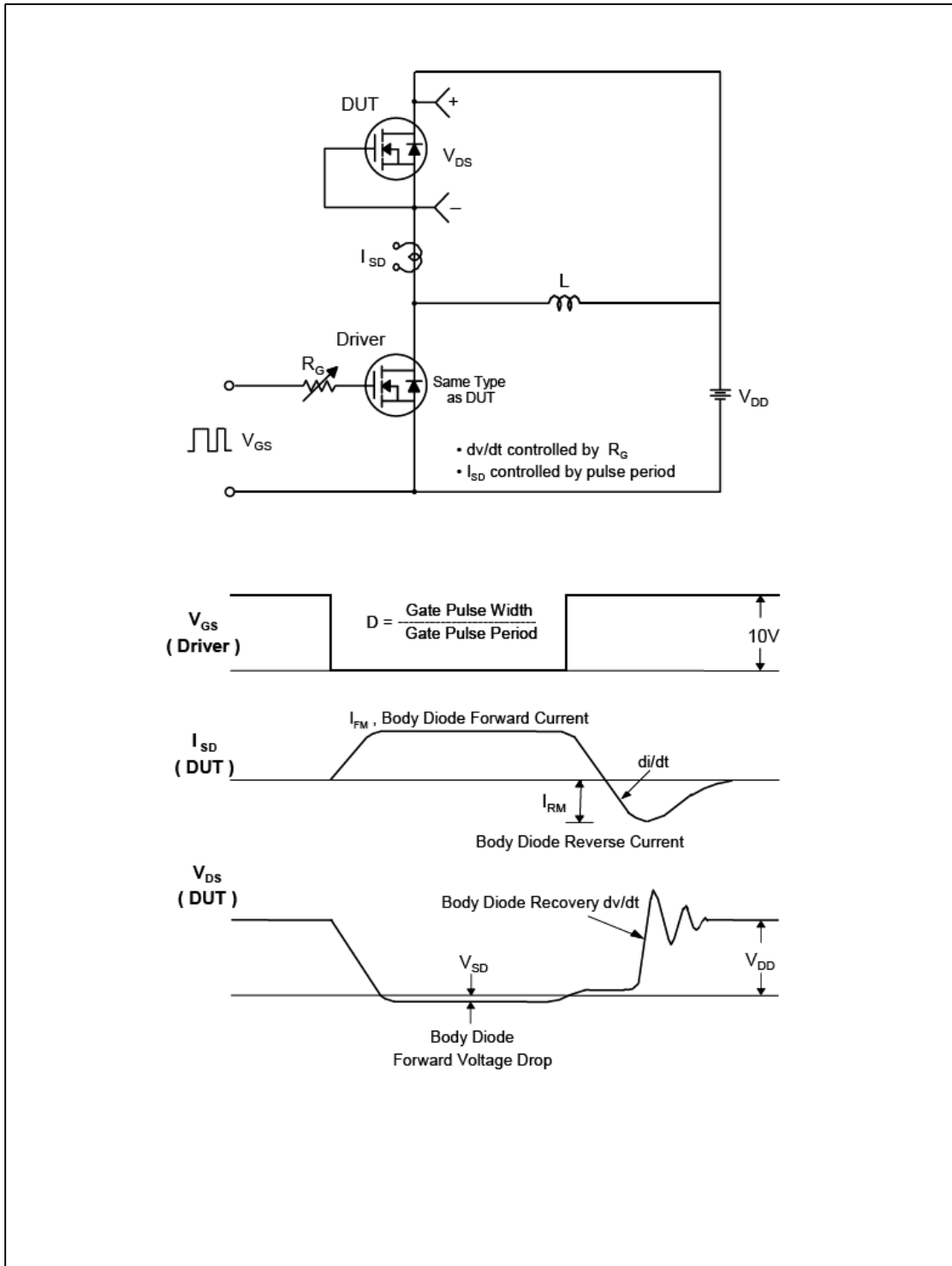
**Fig.10 Gate Test circuit & Waveform**



**Fig.11 Resistive Switching Test Circuit & Waveform**



**Fig.12 Unclamped Inductive Switching Test Circuit & Waveform**



**Fig.13 Peak Diode Recovery dv/dt Test Circuit & Waveform**

